

ADVERTISEMENT FOR BIDS

Highland County, State of Ohio, through its Board of County Commissioners, will receive bids for 2021 Highland County Chip Seal Program as per specifications, until 9:15 A.M., May 5, 2021 at the office of the Highland County Board of Commissioners, 119 Governor Foraker Place, Suite 211, Hillsboro, Ohio 45133 at which time bids will be publicly opened and read aloud. Bids must be delivered to the Clerk of Highland County Commissioners prior to the above-stated time.

Specifications and bid documents for 2021 Highland County Chip Seal Program are on file and may be obtained from the office of Christopher M. Fauber, Highland County Engineer, 138 Bowers Ave, P.O. Box 297, Hillsboro, Ohio 45133. Each bid shall be signed by the full name and business address of each person or company.

Bids shall be accompanied by a Bid Bond for an amount of not less than ten (10%) of the bid amount, or a certified check, on a solvent bank registered to do business in the State of Ohio, for an amount of not less than five percent (5%) of the bid amount.

The owner intends and requires that this project to be completed, no later than August 27, 2021.

The Highland County Board of Commissioners reserves the right to accept the lowest and best bid, reject any and all bids, and to waive any irregularities in bids.

This notice is posted on the Highland County Web site under "Main Menu>Legal Notices" at <http://www.co.highland.oh.us>

By order of the Board of County Commissioners of Highland County, Ohio.

Nicole Oberrecht, Clerk of Board

Please publish the above advertisement on April 20th and send us proof of publication. Thank you.